



Product Change Notification

Change Notification #: 118330- 00
Change Title: MINOR CHANGE: Label Value printed on labels representing the Country of Origin, PCN118330-00, Changing the value from “Fabricated in” to “Made In...with foreign components”
Date of Publication: June 21, 2021

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 21, 2021
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Description of Change to the Customer:

To standardize the marking on the labels and comply with Shipping & Customs best practices for Wafer Sale products, Intel is making three changes on the label placed on the Standard Intermediate Box and the Desiccant Bag.

1) The displayed hard coded header verbiage “Fabricated In” will be replaced with the words, “MADE IN”, followed directly by the actual system pulled value from where the product was fabricated in, plus a new additional statement, “with foreign component”

FROM THIS: FABRICATED IN

TO THIS: MADE IN with foreign component

2) The printed out location of the hard coded header for “MADE INwith foreign components” (formerly “Fabricated In”) will be moved from printing on the right side of the label to be printed on the left side of the label, toward the bottom where it will be rotated and displayed from left to right.

3) Intel is adding a bar code for customers that want to scan in the value for “MADE IN ... with foreign components” (formerly “Fabricated In”). The bar code will be directly under the physically printed value.

AS-IS example (using country Malaysia as an example)



TO-BE example (using country Malaysia as an example)



These changes better represent the source location where wafers are actually being used to make products. For example, “Made In” will be more meaningful to customers rather than “Fabricated In” which represents only where the products are actually fabricated.

Customer Impact of Change and Recommended Action:

Intel considers this change a MINOR CHANGE. There is no change to the product form, fit, function, quality or reliability. This change only impacts the shipping of products and any/all customer customized labels are not in scope for this change.

The type of shipment media impacted by this change are as follows:

- Any product shipped in a Desiccant bag
- Any product shipped in an Intermediate Box (I-Box)

This change will apply only to new labels being printed going forward. Intel will not be relabeling any existing products which have already been packaged, labeled and shelved in their various warehouses.

It is possible for customers to see a mixture of inventory where some have the newer standardized value while others have the prior value until inventory with labels showing the older value are depleted. This could take up to several years.

Please see your Intel Representative with any questions or concerns regarding the communication shared within this product change notification.

Products Affected / Intel Ordering Codes:

Product Code	S-Spec	MM#
X29F32B0R3ATH1	S LMF4	962990
X29F64B0R3ATH1	S LMF6	962992
X29F32B0T3ATH1	S LMKT	975822
X29F64B0T3ATH1	S LMKU	975823
X29F01T0T3AQH1	S LMKV	975824
X29F01T0R3AQH1	S LMKF	976869
X29F32B0T3CMG2	S LMNA	978392
X29F64B0R3ATJ1	S LMXF	986107
X29F64B0T3ATJ1	S LMXH	986109
X29F01T0R3AQJ1	S LN87	999JAX
X29F01T0T3AQJ1	S LN89	999JC0
X29F01T0R3AQK1	S LNL9	99A3FT
X29F01T0T3AQK1	S LNLB	99A3FW
X29F01T0W3AQK1	S LNPT	99A67X
X29F32B0U3ATH1	S LNVR	99AF5D
X29F64B0U3ATH1	S LNVS	99AF5F
X29F01T0U3AQH1	S LNVT	99AF5G
X29F64B0U3ATJ1	S LNVU	99AF5J
X29F01T0U3AQJ1	S LNVV	99AF5K
X29F01T0U3AQK1	S LNVW	99AF5L
X29F01T0D3AQK1	S LNVX	99AF5M
X29F32B0C3ATH1	S LNVY	99AF5P
X29F64B0C3ATH1	S LNVZ	99AF5R
X29F01T0C3AQH1	S LNW2	99AF5T
X29F64B0C3ATJ1	S LNW3	99AF5V
X29F01T0C3AQJ1	S LNW4	99AF5W
X29F01T0C3AQK1	S LNW5	99AF5Z
X29F01T0C3AQKA	S LNZA	99AJKD
X29F01T0U3AQKA	S LNZA	99AJKF
X29F01P0C3AQL1	S LNZA	99AJKJ
X29F01P0U3AQL1	S LNZA	99AJKK

PCN Revision History:

Date of Revision:

June 21, 2021

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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